



PRESS RELEASE

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High-Performance IC Substrate Manufacturing at an Inflection Point

Driven by advanced packaging substrate needs, the industry has reached an inflection point in IC substrate manufacturing. Increasing I/O counts are driving substrate layer counts to more than 20. Larger die sizes and multiple die mounted on the substrate are driving the need for larger body sizes, up to 100 mm x 100 mm. Some companies use a silicon interposer with multiple redistribution layers (RDLs) to provide the connection between logic and high bandwidth memory (HBM). Others use fan-out on substrate with RDLs. A number of companies are considering new RDL on organic solutions with 2 μ m line width and spaces and Intel is exploring an expanded role for its Embedded Multi-die Interconnect Bridge (EMIB). Several companies are making investments in fab-like processing equipment for the next generation IC packaging substrates. These developments are described and a forecast for high-density substrates is provided in TechSearch International's newest Advanced Packaging Update.

TechSearch International's annual survey on substrate design rules is highlighted, with special coverage of suppliers of laminate flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

The latest Advanced Packaging Update is an 85-page report with full references and an accompanying set of 42 PowerPoint slides.

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